

H252-3C0

High Density Server - UP 2U 4 Nodes Server



Features

- 3rd Gen. Intel® Xeon® Scalable Processors
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 32 x DIMMs
- Intel® C621A Express Chipset
- Dual ROM technology supported
- Supports Intel® Optane™ Persistent Memory 200 series
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management port
- 1 x CMC global management port
- 12 x 3.5" or 2.5" SATA/SAS hot-swappable SSD bays
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 2.0 Gen3 x8 mezzanine slots
- 2+0 1600W (240V) 80 PLUS Platinum power supply

Specification

Dimensions	2U 4 Nodes - Rear access (W440 x H87.5 x D695 mm)	Front I/O	-
Motherboard	MH12-HD0	Rear I/O	Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 1 x CMC LAN
CPU	3rd Gen Intel® Xeon® Scalable Processors Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor 10nm technology, CPU TDP up to 270W Total: 4 x LGA 4189 sockets (Socket P+)	Backplane I/O	12 x ports Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s per port
Chipset	Intel® C621A Express Chipset	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
Memory	8-Channel DDR4 memory, total 32 x DIMM slots RDIMM modules up to 64GB supported LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported 1.2V modules: 3200/2933/2666 MHz	Power Supply	2+0 1600W (240V) 80 PLUS Platinum power supply
LAN	8 x 1GbE LAN ports (1 x Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	System Management	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Video	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	OS Compatibility	Windows Server 2016 / 2019 RHEL 8.3 (x64) or later SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
Storage	12 x 3.5" SATA hot-swappable HDD/SSD bays 4 x SATA DOM	System Fans	4 x 80x80x38mm (16,300rpm)
RAID	N/A	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Expansion Slots	8 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x OCP 2.0 mezzanine slot with PCIe Gen3 x8 bandwidth	Packaging Content	1 x H252-3C0, 4 x CPU heatsinks 1 x Rail kit
Internal I/O	Per node: 1 x USB 3.0 header, 1 x SATA DOM, 1 x TPM header, 1 x OCP 2.0 mezzanine slots, 1 x Front panel header, 1 x Back plane board header, 1 x IPMB connector, 1 x Clear CMOS jumper, 1 x BIOS recovery jumper	Reference Numbers	Barebone package: 6NH2523C0MR-00 - Motherboard: 9MZ12HD0NR-00 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320J-A0R - Back plane board: 9CBPH04NR-00 - Power Supply: 25EP0-220008-D0S - Ring topology kit: 6NH262265SR-00-100 (optional extra)

* All specifications are subject to change without notice. Please visit our website for the latest information.

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